

METHOD OF BONDING A CONDUCTIVE ADHESIVE AND AN
ELECTRODE, AND A BONDED STRUCTURE OBTAINED THEREBY

ABSTRACT OF THE DISCLOSURE

5 The present invention relates to a method of bonding
a conductive adhesive and an electrode together, which is
capable of obtaining electrical bonding between a
conductive electrode and an electrode. In this method, a
conductive adhesive containing a conductive filler and an
10 organic binder is coated on an electrode having a layer
formed thereon by plating a low-melting-point material,
and then heated to cure the organic binder and melt the
plated layer on the electrode. As a result, the
conductive filler contained in the adhesive enters the
15 plated layer to obtain strong bonding between the plated
layer and the conductive filler.